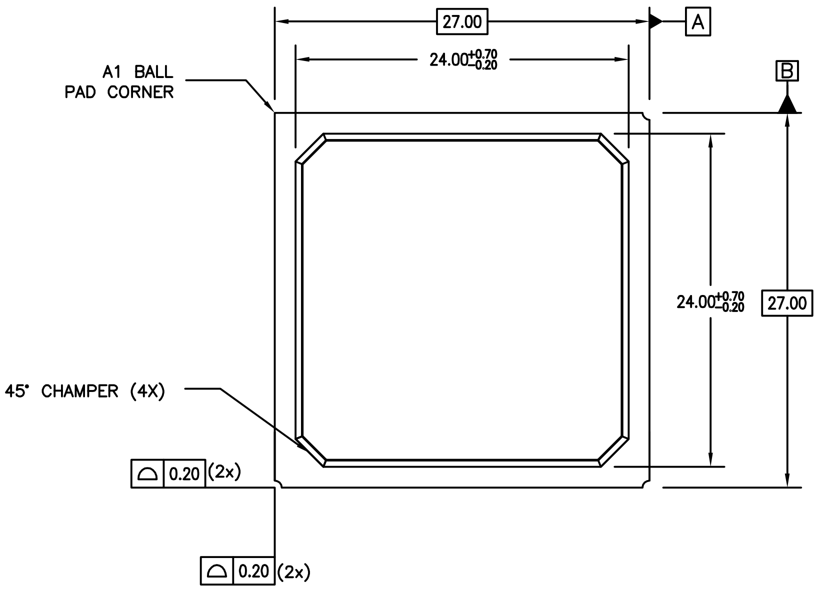
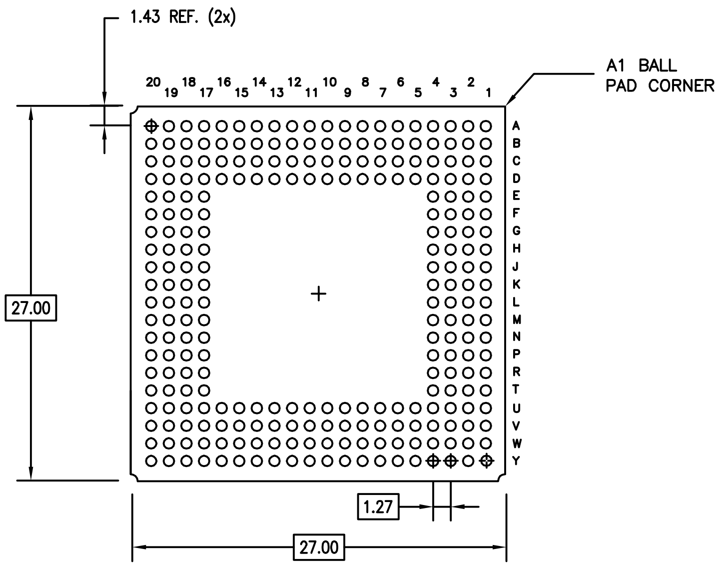
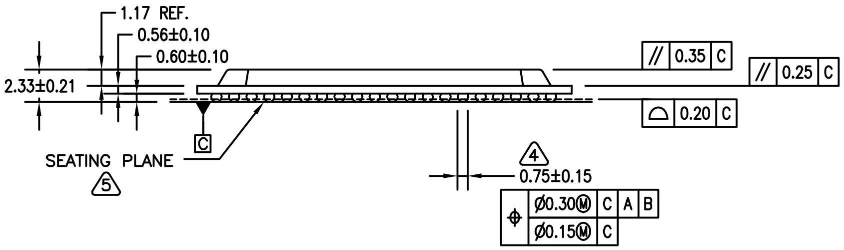


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10−0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.27 MM.

△4 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C

△5 PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO LEADED (−), LEAD FREE (+) PKG. CODES.
8. PACKAGE CODE: V256−2
   V256−3
   V256−5
   V256−6

−DRAWING NOT TO SCALE−

TITLE:
PACKAGE OUTLINE, 256 BALLS PBGA,
27.0x27.0x2.33mm, 1.27mm PITCH, 4 LAYER

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21−0307	B	1/1